

Title (en)
METHOD FOR THE FABRICATION OF AN INTEGRATED ELECTRONIC CIRCUIT AND INTEGRATED ELECTRONIC CIRCUIT THUS OBTAINED

Title (de)
VERFAHREN ZUR ERZEUGUNG EINER INTEGRIERTEN ELEKTRONISCHEN SCHALTUNG UND SO ERHALTENE INTEGRIERTE ELEKTRONISCHE SCHALTUNG

Title (fr)
PROCEDE DE REALISATION D'UN CIRCUIT ELECTRONIQUE INTEGRE ET CIRCUIT ELECTRONIQUE INTEGRE AINSI OBTENU

Publication
EP 1714313 A1 20061025 (FR)

Application
EP 05717608 A 20050210

Priority

- FR 2005000318 W 20050210
- FR 0401482 A 20040213

Abstract (en)
[origin: FR2866471A1] The production of an integrated circuit comprises: (A) forming a portion (1) of a temporary material on a substrate (100), part of which is made of an absorbent material; (B) forming a rigid portion (3, 4) in fixed contact with the substrate, at a side of the temporary material opposite the surface (F) of the part of the substrate of absorbent material; (C) heating the circuit to create a volume essentially empty of material by absorption of the temporary material. The temporary material has a melting point greater than 900 °C and is selected to not provoke any alteration of the material of the parts of the circuit in contact with the temporary material. An independent claim is also included for an integrated circuit produced by this method.

IPC 8 full level
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